

Title (en)
Electroless nickel plating bath composition

Title (de)
Stromlose Vernickelungsbaddzusammensetzung

Title (fr)
Composition de bain pour placage autocatalytique de nickel

Publication
EP 2551375 A1 20130130 (EN)

Application
EP 11175295 A 20110726

Priority
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Abstract (en)
The present invention relates to an aqueous plating bath composition for depositing a nickel phosphorous alloy having a phosphorous content in the range of 5 to 12 wt.-%. The plating bath comprises a sulfur-containing organic stabilising agent.

IPC 8 full level
C23C 18/36 (2006.01)

CPC (source: EP US)
C23C 18/36 (2013.01 - EP US)

Citation (applicant)
• US 2830014 A 19580408 - WOLFGANG GUNDEL, et al
• US 2005013928 A1 20050120 - MARUMO YOSHINORI [JP]

Citation (search report)
• [Y] CH 620710 A5 19801215 - POTAPOV FEDOR PETROVICH, et al
• [Y] GB 2155041 A 19850918 - OMI INT CORP
• [XY] US 2006264043 A1 20061123 - STEWART MICHAEL P [US], et al
• [Y] DATABASE WPI Week 197508, Derwent World Patents Index; AN 1975-13728W, XP002661625

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Designated extension state (EPC)
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DOCDB simple family (application)
EP 11175295 A 20110726; CN 201280036718 A 20120704; EP 12743909 A 20120704; EP 2012062967 W 20120704; JP 2014522015 A 20120704; KR 20147001368 A 20120704; TW 101127003 A 20120726; US 201214131949 A 20120704